SN54ACT563 ... J OR W PACKAGE SN74ACT563 ... DB, DW, N, NS, OR PW PACKAGE

(TOP VIEW)

SCAS550B - NOVEMBER 1995 - REVISED OCTOBER 2002

- 4.5-V to 5.5-V V<sub>CC</sub> Operation
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 8.5 ns at 5 V
- Inputs Are TTL-Voltage Compatible
- 3-State Inverted Outputs Drive Bus Lines Directly
- Flow-Through Architecture to Optimize PCB Layout

## description/ordering information

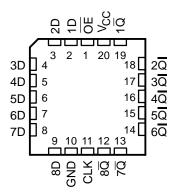
The 'ACT563 devices are octal D-type transparent latches with 3-state outputs. When the latch-enable (LE) input is high, the  $\overline{Q}$  outputs are set to the complements of the data (D) inputs. When LE is taken low, the  $\overline{Q}$  outputs are latched at the inverse logic levels set up at the D inputs.

A buffered output-enable  $(\overline{OE})$  input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased high logic level provide the capability to drive bus lines without interface or pullup components.

OE does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

	•		
OE		$\cup_{20}$	v <sub>cc</sub>
1D	2	19	] 1Q
2D	[] З	18	] 2Q
3D	4	17	] 3Q
4D	5	16	4Q
5D	6	15	] 5Q
6D	7	14	] 6 <mark>Q</mark>
7D	8 ]	13	] 7Q
8D	9	12	8Q
GND	[ 10	11	LE
	-		•

SN54ACT563 . . . FK PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ТА	PACKAGE	≞†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74ACT563N	SN74ACT563N
	SOIC - DW	Tube	SN74ACT563DW	ACT563
-40°C to 85°C	50IC - DW	Tape and reel	SN74ACT563DWR	AC1503
-40°C 10 85°C	SOP – NS	Tape and reel	SN74ACT563NSR	ACT563
	SSOP – DB	Tape and reel	SN74ACT563DBR	AD563
	TSSOP – PW	Tape and reel	SN74ACT563PWR	AD563
	CDIP – J	Tube	SNJ54ACT5634J	SNJ54ACT563J
–55°C to 125°C	CFP – W	Tube	SNJ54ACT563W	SNJ54ACT563W
	LCCC – FK	Tube	SNJ54ACT563FK	SNJ54ACT563FK

### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

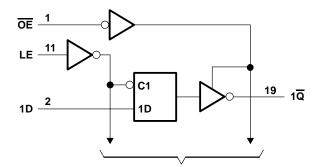


Copyright © 2002, Texas Instruments Incorporated

SCAS550B - NOVEMBER 1995 - REVISED OCTOBER 2002

FUNCTION TABLE (each latch)										
	INPUTS	OUTPUT								
OE	LE	D	Q							
L	Н	Н	L							
L	н	L	н							
L	L	Х	$\overline{Q}_0$							
Н	Х	Х	Z							

## logic diagram (positive logic)



**To Seven Other Channels** 

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Input voltage range, $V_I$ (see Note 1) Output voltage range, $V_O$ (see Note 1) Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) Continuous current through $V_{CC}$ or GND	-0 -0.5 V to V -0.5 V to V -0.5 V to V DB package DW package N package NS package PW package	CC + 0.5 V CC + 0.5 V ±20 mA ±20 mA ±50 mA ±200 mA 70°C/W 58°C/W 69°C/W 60°C/W
Storage temperature range, T <sub>stg</sub>	PW package65°0	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



SCAS550B - NOVEMBER 1995 - REVISED OCTOBER 2002

### recommended operating conditions (see Note 3)

		SN54A	CT563	SN74A	CT563	
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	2	2		V
VIL	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	Vcc	0	VCC	V
Vo	Output voltage	0,	Vcc	0	VCC	V
ЮН	High-level output current	D D	-24		-24	mA
IOL	Low-level output current	20	24		24	mA
$\Delta t / \Delta v$	Input transition rise or fall rate	2	8		8	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		T	A = 25°C	;	SN54A	CT563	SN74A	CT563	
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	1 50 HA	4.5 V	4.4	4.49		4.4		4.4		
	I <sub>OH</sub> = -50 μA	5.5 V	5.4	5.49		5.4		5.4		
Vou	011 - 24 mA	4.5 V	3.86			3.7		3.76		V
Vон	I <sub>OH</sub> = -24 mA	5.5 V	4.86			4.7		4.76		v
	I <sub>OH</sub> = -50 mA <sup>†</sup>	5.5 V				3.85	2			
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					VIE	3.85		
	le 50 uA	4.5 V		0.001	0.1		0.1		0.1	V
	I <sub>OL</sub> = 50 μA	5.5 V		0.001	0.1	~	0.1		0.1	
Ve	le: - 34 mA	4.5 V			0.36	UC D	0.5		0.44	
VOL	I <sub>OL</sub> = 24 mA	5.5 V			0.36	70	0.5		0.44	v
	I <sub>OL</sub> = 50 mA <sup>†</sup>	5.5 V				54	1.65			
	I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V							1.65	
I <sub>OZ</sub>	$V_{O} = V_{CC}$ or GND	5.5 V			±0.25		±5		±2.5	μA
lj	$V_{I} = V_{CC} \text{ or } GND$	5.5 V			±0.1		±1		±1	μA
ICC	$V_{I} = V_{CC} \text{ or GND}, \qquad I_{O} = 0$	5.5 V			4		80		40	μA
$\Delta I_{CC}^{\ddagger}$	One input at 3.4 V, Other inputs at GND or V <sub>CC</sub>	5.5 V		0.6			1.6		1.5	mA
Ci	$V_{I} = V_{CC} \text{ or } GND$	5 V		4.5						pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

<sup>‡</sup>This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

# timing requirements over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

		T <sub>A</sub> = 25°C		SN54ACT563	SN74ACT563		UNIT
		MIN	MAX		MIN	MAX	UNIT
tw	Pulse duration, LE high	3		5	3		ns
t <sub>su</sub>	Setup time, data before LE $\downarrow$	4		4.5	4.5		ns
th	Hold time, data after LE $\downarrow$	0		1.5	0		ns

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SCAS550B - NOVEMBER 1995 - REVISED OCTOBER 2002

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T <sub>A</sub> = 25°C			SN54A	CT563	SN74A	CT563	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	D	Q	3	7	11.5	1	14.5	2.5	12.5	ns
<sup>t</sup> PHL	D	ġ	3	6	10	1	12	2.5	11	115
<sup>t</sup> PLH	LE	Q	3	6.5	10.5	1	12.5	2.5	11.5	20
<sup>t</sup> PHL	LL	ġ	2.5	5.5	9.5	1	<b>Q</b> 11.5	2	10.5	ns
<sup>t</sup> PZH	OE	-	2.5	5.5	9	Q.	11.5	2	10	
<sup>t</sup> PZL	ÛE	Q	2	5.5	8.5	$\overline{\Delta}_{0}$	11	2	9.5	ns
<sup>t</sup> PHZ	ŌĒ	Q	3.5	6.5	10.5	<b>a</b> 1	12	2.5	11.5	200
<sup>t</sup> PLZ	UE	y y	2	4.5	8	1	9.5	1	8.5	ns

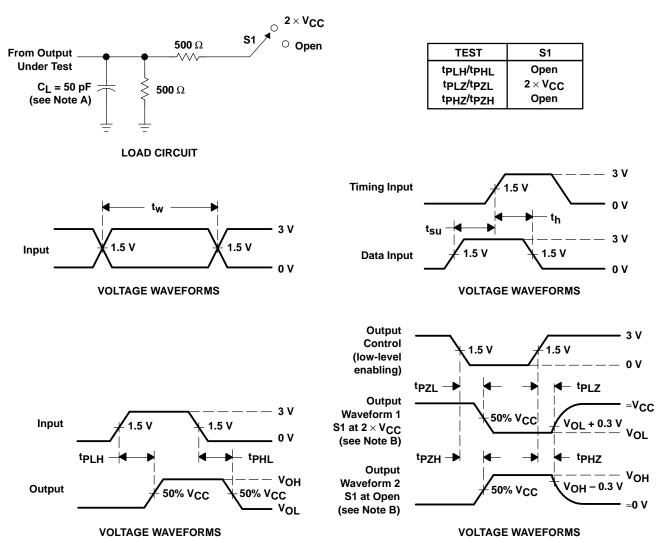
# operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	$C_L = 50 \text{ pF},  f = 1 \text{ MHz}$	50	pF

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SCAS550B - NOVEMBER 1995 - REVISED OCTOBER 2002



### PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.

- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.
- D. The outputs are measured one at a time with one input transition per measurement.

#### Figure 1. Load Circuit and Voltage Waveforms



www.ti.com

11-Nov-2009

## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74ACT563DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74ACT563DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563N	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ACT563NE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ACT563PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74ACT563PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT563PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined. Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements

for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.



#### www.ti.com

11-Nov-2009

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

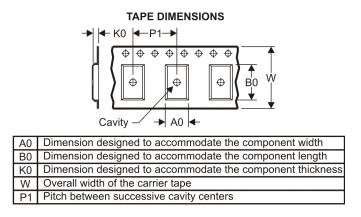
# **PACKAGE MATERIALS INFORMATION**

www.ti.com

Texas Instruments

## **TAPE AND REEL INFORMATION**





# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT563DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ACT563DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ACT563PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TEXAS INSTRUMENTS

www.ti.com

# PACKAGE MATERIALS INFORMATION

5-May-2011



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT563DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74ACT563DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74ACT563PWR	TSSOP	PW	20	2000	346.0	346.0	33.0

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Audio	www.ti.com/audio	Communications and Telecom	www.ti.com/communications
Amplifiers	amplifier.ti.com	Computers and Peripherals	www.ti.com/computers
Data Converters	dataconverter.ti.com	Consumer Electronics	www.ti.com/consumer-apps
DLP® Products	www.dlp.com	Energy and Lighting	www.ti.com/energy
DSP	dsp.ti.com	Industrial	www.ti.com/industrial
Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical
Interface	interface.ti.com	Security	www.ti.com/security
Logic	logic.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Power Mgmt	power.ti.com	Transportation and Automotive	www.ti.com/automotive
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com	Wireless	www.ti.com/wireless-apps
RF/IF and ZigBee® Solutions	www.ti.com/lprf		

**TI E2E Community Home Page** 

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2011, Texas Instruments Incorporated